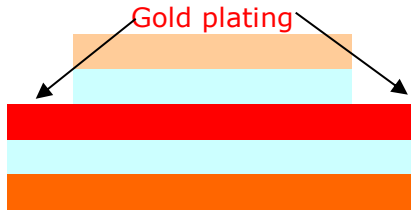




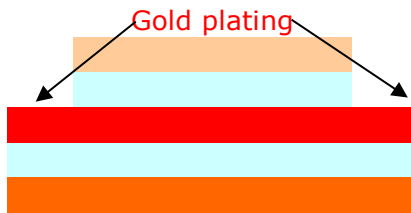
Adhesive material Layer up for 1L Flex circuits



Option A

Polyimide	Coverlay	25	1mil CVL
Adhesive		25	
Copper trace	Base material	35	10Z Copper + 1mil PI
Adhesive		20	
Polyimide		25	
		130 um	

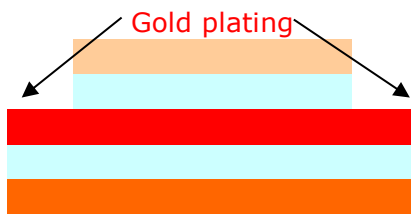
Final thickness **0.13+/-0.03mm**



Option B

Polyimide	Coverlay	25	1mil CVL
Adhesive		25	
Copper trace	Base material	18	1/20Z copper + 1mil PI
Adhesive		20	
Polyimide		25	
		113 um	

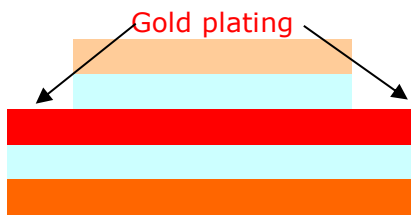
Final thickness **0.11+/-0.03mm**



Option C

Polyimide	Coverlay	25	1mil CVL
Adhesive		25	
Copper trace	Base material	18	1/20Z copper + 1/2mil PI
Adhesive		12	
Polyimide		13	
		92.5 um	

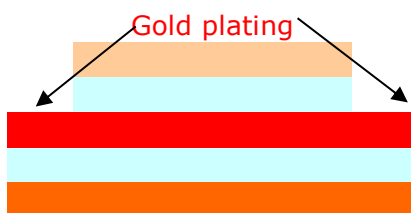
Final thickness **0.09+/-0.03mm**



Option D

Polyimide	Coverlay	12.5	1/2mil CVL
Adhesive		15	
Copper trace	Base material	18	1/20Z copper + 1/2mil PI
Adhesive		12	
Polyimide		13	
		70 um	

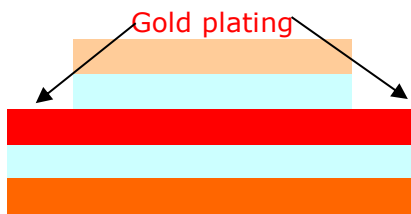
Final thickness **0.07+/-0.03mm**



Option E

Polyimide	Coverlay	12.5	1/2mil CVL
Adhesive		15	
Copper trace	Base material	12	1/30Z copper + 1mil PI
Adhesive		12.5	
Polyimide		25	
		77 um	

Final thickness **0.077+/-0.03mm**



Option F

Polyimide	Coverlay	12	1mil CVL
Adhesive		15	
Copper trace	Base material	18	1/20Z copper + 1mil PI
Adhesive		20	
Polyimide		25	
		90 um	

Final thickness **0.09+/-0.03mm**